CLAIMS

1. A circuit component comprising:

a first structure having first and second opposing surfaces and provided from an elastically deformable material; and

a second structure having first and second opposing surfaces, with the first surface of said first structure disposed proximate the first surface of said second structure; and

a support structure disposed between the first surface of said first structure and the first surface of said second structure such that the support structure acts as a fulcrum about which said first structure can be elastically deformed, causing at least a portion of the first surface of said first structure to move relative to the first surface of said second structure.

2. The circuit component of Claim 1, further comprising:

a conductor disposed on the first surface of said first structure in a first conductive region; and

a conductor disposed on the first surface of said second structure in a second conductive region, wherein the first conductive region and the second conductive region are separated by a gap, forming a capacitor.

3. The circuit component of Claim 2, wherein the capacitor has a capacitance which varies in proportion to variations of the gap formed between the first conductive region and the second conductive region in response to elastic deformation of said first structure.

4. The circuit component of Claim 2, further comprising:

a conductor disposed on the first surface of said first structure in a third conductive region coupled to the first conductive region;

a conductor disposed on the first surface of said second structure in a fourth conductive region coupled to the second conductive region, wherein the third and fourth conductive regions form an inductor in parallel with the capacitor.

5. The circuit component of Claim 4, wherein the capacitor has a capacitance which varies in proportion to variations of the gap formed between the first conductive region and the second conductive region in response to elastic deformation of said first structure, and wherein the inductor has an inductance, which is essentially constant.

6. The circuit component of Claim 1, further including conductive layers disposed on the first surface of each of the first and second structures, forming a zipper actuator adapted to elastically deform the first structure in response to a voltage applied between the conductive layers.

7. A method of making a circuit component, comprising:

processing an elastically deformable wafer having first and second opposing surface to provide a first structure;

forming a second structure having first and second opposing surfaces;

processing a selected one of the first structure and the second structure to provide a support structure; and

bonding the support structure to the unselected one of the first structure and the second structure such that the support structure acts as a fulcrum about which said first structure can be elastically deformed, causing at least a portion of the first surface of said first structure to move relative to the first surface of said second structure.

8. The method of Claim 7, wherein the first structure is silicon, the second structure is a selected one of glass and quartz, and the selected one of the first structure and the second structure is the first structure.

9. The method of Claim 8, wherein the bonding step includes anodic bonding.

10. The method of Claim 9, wherein the first structure is silicon and the second structure is

silicon.

11. The method of Claim 10, wherein the bonding step includes fusion bonding.

12. The method of Claim 7, further comprising:

processing the first surface of the first structure to provide a first conductive region; and

processing the first surface of the second structure to provide a second conductive region, wherein the first conductive region and the second conductive region are separated by a gap, forming a capacitor.

13. The method of Claim 12, wherein the capacitor has a capacitance which varies in proportion to a variable gap formed between the first conductive region and the second conductive region in response to elastic deformation of said first structure.

14. The method of Claim 12, further comprising:

processing the first surface of the first structure to provide a third conductive region coupled to the first conductive regions; and

processing the first surface of the second structure to provide a fourth conductive region coupled to the second conductive region, wherein the third and fourth conductive regions form an inductor in parallel with the capacitor.

15. The method of Claim 14, wherein the capacitor has a capacitance which varies in proportion to a variable gap formed between the first conductive region and the second conductive region in response to elastic deformation of said first structure, and wherein the inductor has an inductance which is essentially constant.

16. The method of Claim 7, further including forming conductive layers on the first surface of each of the first and second structures, forming a zipper actuator adapted to elastically deform the first structure in response to a voltage applied between the conductive layers.